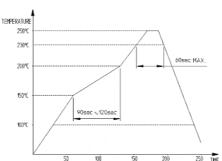
REV	COUNT	NT DESCRIPTION OF REVISIO			BY KYG	CHKD LHJ	DATE 21.08.30	REV	COUNT 1	_	ESCRIPTION OF REVISION	ONS BY	CHKD LHJ	<del>                                     </del>	ATE 02.07		
$\Delta$	<ul><li>Revised</li><li>Revised</li></ul>				KYI	LHJ	21.12.16	/ <u>3</u> \	4	_	-2-2139 -2-2437	LHJ		0.24			
Universal Serial Rus							21.12.16 4 4 RE-2-2437 OSW LHJ								0.2		
Universal Serial Bus Ty							ype-C Connectors and Cable Assemblies Compliance Document Revision 2.1b										
RATING CORRENT 1.25A ma					25A max	0A max. for each power pin (i.e. A1, A4, A9, A12, B1, B4, B9, B12) 5A max. for VCON(i.e. B5), 0.25A for the other pins											
VOLTAGE 48V AC/DC								. \ 05	-0/ 5		. \						
							icluding Temp. rise), 95% RH Max. (Non-condensing)										
Para.							roced		76 707	70 T 11		Test Requirement					
1	1 Examination of product				34-18 inspectio	on				No physical damage.	0	0					
Electr	rical Re	equirer	ments														
2	Low Level Contact				64-23 ire at 20r imA max imeasure sistance o be deduct	. (DC or ement is of PCB t	1000Hz required terminati	) d and on		Initial:40mΩ max After test:50mΩ max	0	1					
3	Dielectric Withstanding Voltage				64-20 ire per Mo ed condi AC RMS 1	tion.		ea leve	I.	No disruptive discharg	0	1					
4	4 Insulation Resistance				34–21 DC with u	ınmated	and ma	ted cor	ndition.	100MΩ min.	0	-					
Mech	anical	Requi	rements														
5	FIA 364-13					5mm/m	Initial: 5N ~ 20N After test: 5N ~ 20N (with virgin pl					olug)	0	-			
6	Extraction force				EIA 364-13 Measure at 12.5mm/minute min.						Initial: 8N ~ 20N After test: 6N ~ 20N	0	-				
7	Mating stroke Insertion, ext				10,000 tanically of stroke: on, extra	10,000 times					No physical damage.	0					
8	EIA 364-28 Test Condition VII, Test Lette Mated specimens to 3.10 G' between 20 to 500Hz 15 minutes in each of 3 mut perpendicular planes.				10 G's F	0 G's RMS			No physical damage. No discontinuity of 1µs of longer duration when mated connector during test.				_				
REMARKS					DRA	\FT	DES	SIGN	N CHECK A	PPROVAL	REL	EAS	E				
					Y.B.F		Y.B.I				DE 23.1	0.2	4				
						21.0	8.05	21.08.05 21.08.05 21.08.05			EI	١G					
NOTE) QT : QUALIFICATION TEST, AT : ASSURANCE TEST, O : Applicable Test								_									
DWG N	0				CL NO						PART NO						
ELC4-633145-00 CL 624						249-0002-9-000 CX90MW6-16P											
HS HIROSE KOREA.CO.,LTD						PRODUCT SPECIFICATION 1/3											

	Ś
	ヹ
	ဗ
	/e equipment / device which demand high reliability, kindly contact our sales window correspondents.
	g
	ĕ
	2
	0
	S
	ğ
	₹
	S
	<u></u>
	SS
	₽
8	0
≝	ಜ್ಞ
se	쁄
ĕ	õ
ıΫ́	>
۲	ਰੂ
<u></u>	÷
~	$\overline{}$
₹	≝
<u>.</u>	چ
Ħ	쓽
_	2
o.	늉
$\ddot{\circ}$	Ē
$\circ$	g
~	ğ
=	Ä
Щ	ŏ
_	등
111	≊
$\overline{S}$	≥
$\gtrsim$	8
\#	⅀
7	ŏ
Š	<u>'</u>
$\approx$	e
Ħ	Ē
5	.≘
Copyright 2025 HIROSE ELECTRIC CO., LTD. All Rights Reserved.	ğ
ত্	ψ.
$\mathcal{C}$	≝.
2	ಠ
2	
÷	ಕ
⋽	⋖
7	p
	.≌
	_
	9
	H
	≓
	37.5
	<u>ĕ</u>
	S
	ő
	₹
	9
	386
	ၓ
	_

Para.	Test Description	Test Procedure	Test Requirement	QT	АТ
Envir	onmental Requirements				
9	Temperature Life	EIA 364-17, Method A 105°C without applied voltage for 120 hours.	No physical damage.	0	-
10	Cyclic Temperature and Humidity	EIA 364-31 25±3°C at 80±3% RH for 1 hour. 65±3°C at 50±3% RH for 1 hour. Thermal ramp: 0.5 hour Number of cycles: 24 cycles	No physical damage.	0	_
11	Thermal Shock	EIA 364-32 10 cycles -55°C and +105°C	No physical damage.	0	_
12	Solderability	EIA 364-52 Dwell in 245±5℃ of the solder bath for 5 sec.	Solder coverage shall be 95% min. of the immersed surfaces.	0	_
13	Salt Spray	EIA 364-26 5% of NaCl in 35℃ for 48 hours.	No corrosions that affect to the connector operation.	0	-
14	Co-Planarity	Measure Co-planarity of each contact lead.	0.08 Max before reflow. 0.10 Max after reflow 2times.	0	_
15	High Temperature and Humidity	EIA-364-31 High-temperature 85℃/85% RH for 120 hours.	No physical damage. No change to performance.	0	_
16	IPX8	IEC 60529 Immersion in the water at the depth of 1.5m for 30min.	No water leakage.	0	_
17	⚠ IP6X	IEC 60529 Duration: 8hours at least. Amount of talcum powder of the test chamber: 2 kg/m^3 Dust type: Talcum Powder (less than 75µm)	No ingress of dust	0	_
18	Temperature Rise	IEC60529, EIA-364-70, method B: A current of 6.0 A shall be applied collectively to VBUS pins (i.e., pins A4, A9, B4, and B9) and 1.5 A applied to the Vconn pin (i.e., B5 of the plug connector) with the return path through the corresponding GND pins (i.e., pins A1, A12, B1, and B12). A minimum current of 0.25 A shall also be applied individually to all the other contacts.	Temperature rise shall not exceed 30℃	0	_
19	Reflow Heat	Reflow profile [Fig.1] Peak 250°C max for 10 sec 2 times.	No deformation of mold No shape of blister and popcorn	0	_



(3) [Fig.1] REFLOW TEMPERATURE

NOTE) QT : QUALIFICATION TEST, AT : ASSURANCE TEST, O : Applicable Test

DWG NO CL NO PART NO

ELC4-633145-00 | CL 6249-0002-9-000

CX90MW6-16P

HIS HIROSE KOREA.CO.,LTD

PRODUCT SPECIFICATION

Qualification Test Sequence Table												
Daza	Total Day 1.11	Test Group										
Para.	Test Description		В	С	D	Е	F	G	Н	I	J	К
1	Examination of product	1, 6	1, 14	1, 6	1, 6	1, 6	1, 3	1, 6	1, 4	1, 4	1, 4	1,9
2	Low Level Contact Resistance	3, 5	3, 13	3, 5	3, 5	3, 5		3, 5				3,8
3	Dielectric Withstanding Voltage		4, 12									
4	Insulation Resistance		5, 11									
5	Insertion force		6, 10									
6	Extraction force		7, 9									
7	Durability		8									4
8	Random Vibration											
9	Temperature Life			4								
10	Cyclic Temperature and Humidity				4							
11	Thermal Shock					4						5
12	Solderability						2					
13	Salt Spray							4				
14	Co-planarity								3			
15	4 High Temperature and Humidity											6
16	IPX8									3		
17	<u></u> IP6X											7
18	Temperature Rise										3	
19	Reflow Heat		2	2	2	2		2	2	2	2	2

## REMARKS

1) Numbers in the table above indicate the sequence corresponding to each test group.

NOTE) QT : QUALIFICATION TEST, AT : ASSURANCE TEST, 0 : Applicable Test

DWG NO

ELC4-633145-00

CL 6249-0002-9-000

CX90MW6-16P

**H**S +

HIROSE KOREA.CO.,LTD